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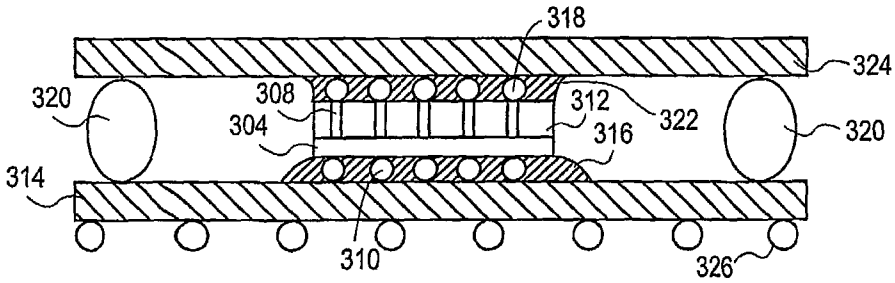
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(54) Title: METHOD AND APPARATUS FOR A DUAL SUBSTRATE PACKAGE



(57) Abstract: A semiconductor die having a through via formed therein is disclosed. A first conductive layer is formed on the front side of the die and a second conductive layer is formed on the backside of the die, and coupled with the through via. A first package substrate is electrically coupled with the first conductive layer, and a second package substrate is electrically coupled with the second conductive layer. In another embodiment, a substrate ball electrically couples the first and second package substrates. In a further embodiment, a flip chip bump is attached to the first package substrate.

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